SPS252010U SERIES

1. PART NO. EXPRESSION:

SPS252010U1R0Y

(a) Series code

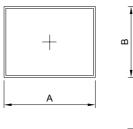
(d) Inductance code : 1R0 = 1.0 μ H

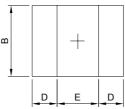
(c) (d) (e)

(b) Dimension code (c) U: Uncoated

(e) Tolerance code: M=±20% Y=±30%

2. CONFIGURATION & DIMENSIONS:







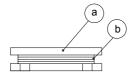
Unit:m/m

А	В	С	D	E
2.50± 0.1	2.20± 0.1	1.0 max.	0.85 ref.	0.80 ref.

3. SCHEMATIC:



4. MATERIALS:



(a) Core: Ferrite Core

(b) Wire: Copper Wire

5. GENERAL SPECIFICATION:

a) Isat : Based on inductance change (△L/L0 : ≦-30%) @ ambient temp. 25°C

b) Irms: Based on temperature rise ($\triangle T$: 40°C.)

c) Storage temp.: -40° C to +105° C, 50-60%RH (Product without taping)

d) Operating temp. : -40° C to +105° C

e) Resistance to solder heat: 260±5° C 10±0.5secs



NOTE: Specifications subject to change without notice. Please check our website for latest information.

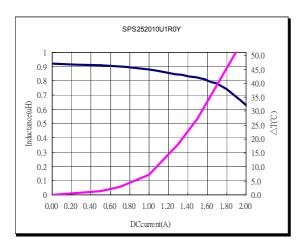


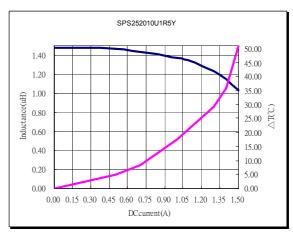
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6. ELECTRICAL CHARACTERISTICS:

Part Number	Inductance (µH)	Tolerance (%)	Test Frequency (Hz)	DCR (Ω) ±20%	Isat (A) Typ.	Isat (A) Typ.
SPS252010U1R0Y	1.0	± 30%	0.1V/1M	0.086	2.60	1.70
SPS252010U1R5Y	1.5	± 30%	0.1V/1M	0.112	2.20	1.40
SPS252010U2R2M	2.2	± 20%	0.1V/1M	0.180	1.70	1.10
SPS252010U3R3M	3.3	± 20%	0.1V/1M	0.256	1.40	1.00
SPS252010U4R7M	4.7	± 20%	0.1V/1M	0.390	1.10	0.70
SPS252010U6R8M	6.8	± 20%	0.1V/1M	0.520	0.90	0.60
SPS252010U100M	10	± 20%	0.1V/1M	0.820	0.80	0.50

7. CHARACTERISTIC CURVES:





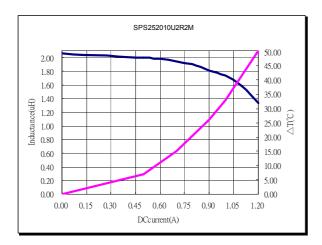


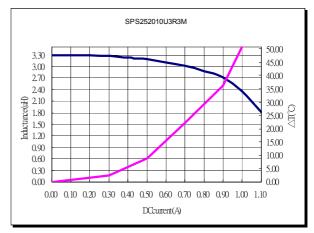
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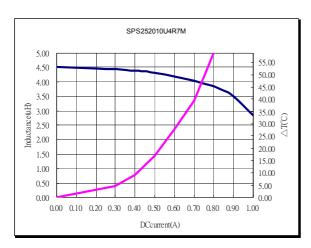


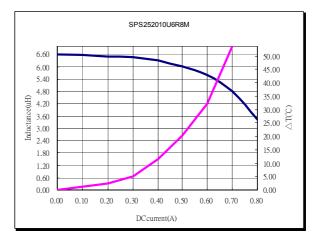
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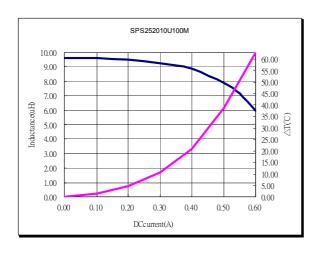
7. CHARACTERISTIC CURVES:













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8. RELIABILITY & TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION
Operating Temperature	-40 to +105° C	
Storage Temperature	-40 to +105° C, 50-60%RH Product without taping	
Rated Current	Base on temp. rise & △L/L0A ≦ 30%.	Saturation DC current (Isat) will cause L0 to drop approximately \triangle L(%)
Temperature Rise Test	40°C max. (Δt)	Heat Rated Current (Irms) will cause the coil temperature 1. Applied the allowed DC current 2. Temperature measured by hte digital surface thermometer
Solder Heat Resistance	Appearance : No significant abnormality Impedance change : Within ± 20% Preheating Dipping Natural cooling 150° C 150° C 150° C 10±0.5 seconds	Preheat: 150° C, 60sec. Solder: Sn-Cu0.5% Solder Temperature: 260±5° C Flux for lead free: rosin Dip Time: 10±0.5sec.
Solderability	More than 90% of the terminal electrode should be covered with solder. Preheating Dipping Natural cooling 150° C 60	Preheat: 150° C, 60sec. Solder: Sn-Ag3.0-Cu0.5 Solder Temperature: 245±5° C Flux for lead free: rosin Dip Time: 4±1sec.
Thermal shock	Appearance: no damage Inductance: within± 20% initial value Phase	Condition for 1 cycle Step 1: -55+0/-2° C 15± 1 min. Step 2: Room temperature 5 min. Step 3: +85 +2/-0° C 15± 1min. Step 4: Room temperature 5 min. Number of cycles: 100
Humidity Resistance Test	Appearance: No damage. Impedance: Within ± 20% of initial value.	Humidity: 90~95% RH. Temperature: 40±2° C Duration: 500 hrs Measured at room temperature after placing for 2 to 3hrs.



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8. RELIABILITY & TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION
High Temp. Resistance Test	Appearance : No damage. Impedance : Within ± 20% of initial value.	Temperature : -40± 2° C Applied current : rated current Duration : 500 hrs
Low Temp. Life Test	Appearance : No damage. Impedance : Within ± 20% of initial value.	Temperature : 105± 2° C Duration : 500 hrs
Random Vibration Test	Appearance : Cracking, shipping & any other defects harmful to the characteristics should not be allowed. Impedance : Within ± 20%	Frequency: 10-55-10Hz for 15 min. Amplitude: 1.52mm Directions & times: X, Y, Z directions for 15 mins. this cycle shall be perfromed 12 times in each of the three mutually perpendicular directions. (Total 9hours).

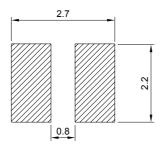


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9. SOLDERING AND MOUNTING:

9-1. Recommended PC Board Pattern



9-2. Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. The terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

9-2.1 Lead Free Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

9-2.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note:

- a) Preheat circuit and products to 150° C.
- b) 355° C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4-5 secs.

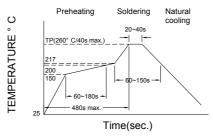


Figure 1. Re-flow Soldering

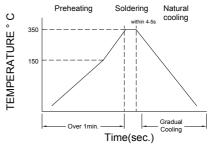


Figure 2. Hand Soldering



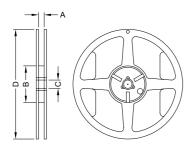
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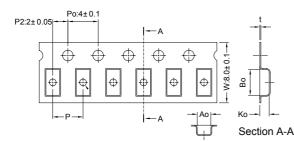
10. PACKAGING INFORMATION:

10-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
7" x 8mm	8.4± 1.0	50 min	13.0± 0.8	178.0± 2.0

10-2 Tape Dimension / 8mm



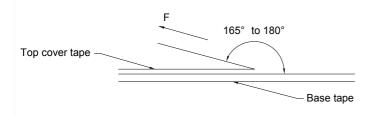
7" x 8mm

Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
SPS	252010	2.74± 0.1	2.27± 0.1	1.18± 0.1	4.0± 0.1	0.23± 0.05	none

10-3. Packaging Quantity

Chip Size	252010	
Chip / Reel	2000	

10-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed (mm/min)
(° C)	(%)	(hPa)	
5~35	45~85	860~1060	300

Application Notice

1. Storage Conditions:

To maintain the solderability of terminal electrodes :

- a) Temperature and humidity conditions : $-10 \sim 40^{\circ}$ C and $30 \sim 70\%$ RH.
- b) Recommended products should be used within 6 months from the time of delivery.
- c) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



RoHS Compliant

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01.09.2011



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